

IN THE CLAIMS:

1. (Currently Amended) A package ~~for~~ containing a semiconductor element comprising:

a housing ~~having a recess portion for~~ containing a semiconductor element, said housing having two primary side walls that are perpendicular to each other; and
a pair of positioning holes and a pair of attaching holes respectively provided at opposed side portions of said housing,

wherein a line between said pair of positioning holes and a line between said pair of attaching holes intersect with each other substantially at a center of said package and further wherein the line between the positioning holes is skewed with respect to each of the two primary side walls of the housing and the line between the attaching holes is skewed with respect to each of the primary side walls such that the line between the positioning holes and the line between the attaching holes are each neither parallel nor perpendicular to either of the primary side walls.

2. (Original) The package according to claim 1:

wherein said semiconductor element is a solid-state imaging element.

3. (Currently Amended) A semiconductor device comprising:

a semiconductor element;

a housing ~~having a recess portion for~~ containing said semiconductor element, said housing having two primary side walls that are perpendicular to each other; and

a pair of positioning holes and a pair of attaching holes respectively provided at opposed side portions of said housing;

wherein a line between the pair of positioning holes and a line between said pair of attaching holes intersect with each other substantially at a center of said package and further wherein the line between the positioning holes is skewed with respect to each of the primary side walls of the housing and the line between the attaching holes is skewed with respect to each of the primary side walls such that the line between the positioning holes and the line between the attaching holes are each neither parallel nor perpendicular to either of the primary side walls.

4. (Original) The semiconductor device according to claim 3,

wherein said semiconductor element is a solid-state imaging element.

5. (Currently Amended) A semiconductor device comprising:

a semiconductor element;

a housing ~~having a recess portion for containing said semiconductor element, said~~
housing having two primary side walls that are perpendicular to each other;

a pair of attaching holes provided at opposed side portions of said housing at a surface of said package; and

a transparent member for sealing said semiconductor element in ~~said a recess portion;~~

wherein said surface of said housing is made to be higher than a top surface of said transparent member, and further wherein a line between the pair of positioning holes and a line between said pair of attaching holes intersect with each other substantially at a center of said package and further wherein the line between the positioning holes is skewed with

respect to each of the primary side walls of the housing and the line between the attaching holes is skewed with respect to each of the primary side walls such that the line between the positioning holes and the line between the attaching holes are each neither parallel nor perpendicular to either of the primary side walls.

6. (Original) The semiconductor device housing according to claim 5,
wherein said semiconductor element is a solid-state imaging element.